

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-65. (Cancelled)

66. (New) A method for producing a laminate for an electronic circuit component, comprising:

providing a first inorganic material layer/a first insulating layer/a second inorganic material layer or a second layer construction of the inorganic material layer/the first insulating layer, at least the first insulating layer having a multi-layer structure including at least a first resin layer and a second resin layer; the first resin layer having a first etching rate when etched with an alkali-aliphatic amine solution and the second resin layer having a second etching rate when etched with the alkali-aliphatic amine solution; and

wet-etching the first or second layer construction with an alkali-aliphatic amine solution so that a ratio of the first etching rate to the second etching rate is from 4:1 to 1:1, thereby controlling a shape of an edge of the laminate after etching.